

TRS202E 具有 $\pm 15\text{kV}$ IEC ESD 保护功能的 5V 双路 RS-232 线路驱动器和接收器

1 特性

- 用于 RS-232 总线引脚的 IEC61000-4-2 (4 级) ESD 保护 :
 - $\pm 8\text{kV}$ 接触放电
 - $\pm 15\text{kV}$ 气隙放电
 - $\pm 15\text{kV}$ 人体放电模型
- 符合或超出 TIA/EIA-232-F 和 ITU v.28 标准的要求
- 由 5V V_{CC} 电源供电
- 速率高达 120kbit/s
- 外部电容器 : 4 个 $0.1\mu\text{F}$ 或 4 个 $1\mu\text{F}$
- 闩锁性能超过 100mA , 符合 JESD 78 II 级规范

2 应用

- 电池供电型系统
- 笔记本电脑
- 便携式计算机
- 机顶盒
- 手持设备

3 说明

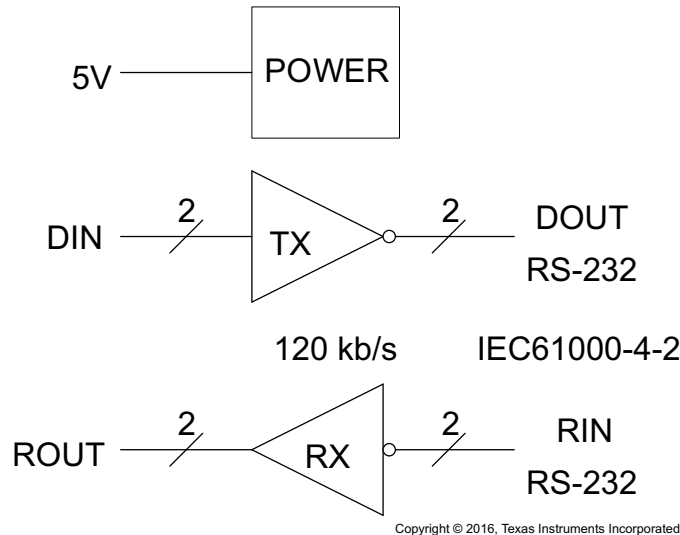
TRS202E 由两个线路驱动器、两个线路接收器和一个双路电荷泵电路组成。TRS202E 具有 IEC61000-4-2 (4 级) ESD 引脚对引脚 (串行端口连接引脚, 包括 GND) 保护。该器件符合 TIA/EIA-232-F 的要求并在异步通信控制器与串行端口连接器之间提供电气接口。电荷泵和四个小型外部电容器支持由单个 5V 电源供电。该器件以高达 120kbit/s 的数据信号传输速率和最高 $30\text{V}/\mu\text{s}$ 的驱动器输出压摆率运行。

封装信息

器件型号	封装 ⁽¹⁾	封装尺寸 ⁽²⁾
TRS202E	SOIC (D) (16)	9.9mm x 6mm
	SOIC (DW) (16)	10.4mm x 10.3mm
	PDIP (N) (16)	19.3mm x 9.4mm
	TSSOP (PW) (16)	5mm x 6.4mm

(1) 如需更多信息, 请参阅节 10。

(2) 封装尺寸 (长 × 宽) 为标称值, 并包括引脚 (如适用)。



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逻辑图 (正逻辑)



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4 Pin Configuration and Functions

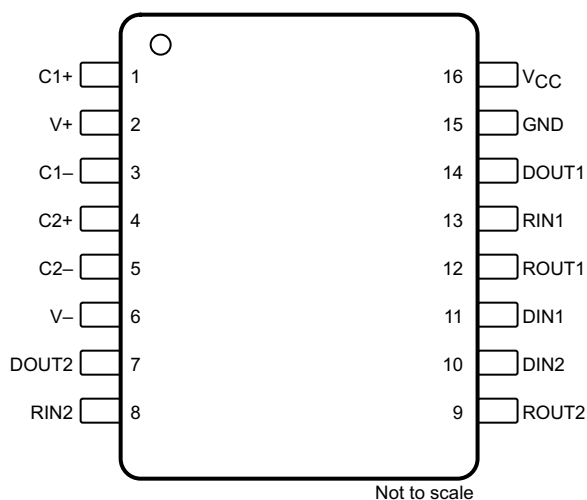


图 4-1. D, DW, N or PW Package, 16-Pin SOIC or TSSOP
(Top View)

表 4-1. Pin Functions

PIN		I/O	DESCRIPTION
NO.	NAME		
1	C1+	—	Positive lead of C1 capacitor
2	V+	O	Positive charge pump output for storage capacitor only
3	C1 -	—	Negative lead of C1 capacitor
4	C2+	—	Positive lead of C2 capacitor
5	C2 -	—	Negative lead of C2 capacitor
6	V -	O	Negative charge pump output for storage capacitor only
7	DOUT2	O	RS-232 line data output (to remote RS-232 system)
8	RIN2	I	RS-232 line data input (from remote RS-232 system)
9	ROUT2	O	Logic data output (to UART)
10	DIN2	I	Logic data input (from UART)
11	DIN1	I	Logic data input (from UART)
12	ROUT1	O	Logic data output (to UART)
13	RIN1	I	RS-232 line data input (from remote RS-232 system)
14	DOUT1	O	RS-232 line data output (to remote RS-232 system)
15	GND	—	Ground
16	V _{CC}	—	Supply voltage, connect to external 5-V power supply

5 Specifications

5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)^{(1) (2)}

		MIN	MAX	UNIT
Supply voltage, V_{CC} ⁽²⁾		- 0.3	6	V
Positive charge pump voltage, V_{+} ⁽²⁾		$V_{CC} - 0.3$	14	V
Negative charge pump voltage, V_{-}		- 14	0.3	V
Input voltage, V_I	Drivers	- 0.3	$V_{+} + 0.3$	V
	Receivers		± 30	
Output voltage, V_O	Drivers	$V_{-} - 0.3$	$V_{+} + 0.3$	V
	Receivers	- 0.3	$V_{CC} + 0.3$	
Short-circuit duration, D_{OUT}		Continuous		
Operating virtual junction temperature, T_J			150	°C
Storage temperature, T_{stg}		- 65	150	°C

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) All voltages are with respect to network GND.

5.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$ Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	Pins 7, 8, 13, 14, 15	± 15000	V
		All other pins	± 2000	
	Charged-device model (CDM), per JEDEC specification JESD22-C101 ⁽²⁾	All pins	± 1500	
	IEC 61000-4-2 contact discharge	Pins 7, 8, 13, 14, 15	± 8000	
	IEC 61000-4-2 air-gap discharge	Pins 7, 8, 13, 14, 15	± 15000	

(1) JEDEC document JEP155 states that 500V HBM allows safe manufacturing with a standard ESD control process.

(2) JEDEC document JEP157 states that 250V CDM allows safe manufacturing with a standard ESD control process.

5.3 Recommended Operating Conditions

see 图 7-1 ⁽¹⁾

		MIN	NOM	MAX	UNIT
Supply voltage		4.5	5	5.5	V
V_{IH}	Driver high-level input voltage (D_{IN})	2			V
V_{IL}	Driver low-level input voltage (D_{IN})			0.8	V
V_I	Driver input voltage (D_{IN})	0		5.5	V
	Receiver input voltage	- 30		30	
T_A	Operating free-air temperature	TRS202EC		0	°C
		TRS202EI		- 40	

(1) Test conditions are C1 to C4 = 0.1 μ F at V_{CC} = 5V $\pm$ 0.5V.

5.4 Thermal Information

THERMAL METRIC ⁽¹⁾		D (SOIC)	DW (SOIC)	N (PDIP)	PW (TSSOP)	UNIT
		16 PINS	16 PINS	16 PINS	16 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	84.6	77.1	44.1	107.5	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	43.5	39.9	30.8	38.4	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	43.2	41.8	24.2	53.7	°C/W
ψ_{JT}	Junction-to-top characterization parameter	10.4	12.9	15.2	3.2	°C/W
ψ_{JB}	Junction-to-board characterization parameter	42.8	41.3	24	53.1	°C/W

- (1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

5.5 Electrical Characteristics

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted; see 图 7-1)⁽¹⁾

PARAMETER	TEST CONDITIONS	MIN	TYP ⁽²⁾	MAX	UNIT
I_{CC}	Supply current	No load, $V_{CC} = 5V$		8	15 mA

- (1) Test conditions are C1 to C4 = 0.1μF at $V_{CC} = 5V + 0.5V$.
(2) All typical values are at $V_{CC} = 5V$ and $T_A = 25^\circ C$.

5.6 Electrical Characteristics: Driver

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see 图 7-1)⁽¹⁾

PARAMETER	TEST CONDITIONS	MIN	TYP ⁽²⁾	MAX	UNIT
V_{OH}	High-level output voltage	D_{OUT} at $R_L = 3k\Omega$ to GND, $D_{IN} = GND$		5	9 V
V_{OL}	Low-level output voltage	D_{OUT} at $R_L = 3k\Omega$ to GND, $D_{IN} = V_{CC}$		- 5	- 9 V
I_{IH}	High-level input current	$V_I = V_{CC}$		15	200 μA
I_{IL}	Low-level input current	V_I at 0V		- 15	- 200 μA
I_{OS} ⁽³⁾	Short-circuit output current	$V_{CC} = 5.5V$ and $V_O = 0V$		±10	±60 mA
r_o	Output resistance	V_{CC} , V_+ , $V_- = 0V$, and $V_O = \pm 2V$		300	Ω

- (1) Test conditions are C1 to C4 = 0.1μF at $V_{CC} = 5V + 0.5V$.
(2) All typical values are at $V_{CC} = 5V$ and $T_A = 25^\circ C$.
(3) Short-circuit durations must be controlled to prevent exceeding the device absolute power-dissipation ratings, and not more than one output must be shorted at a time.

5.7 Electrical Characteristics: Receiver

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted; see 图 7-1)⁽¹⁾

PARAMETER	TEST CONDITIONS	MIN	TYP ⁽²⁾	MAX	UNIT
V_{OH}	High-level output voltage	$I_{OH} = - 1mA$		3.5	$V_{CC} - 0.4$ V
V_{OL}	Low-level output voltage	$I_{OL} = 1.6mA$			0.4 V
V_{IT+}	Positive-going input threshold voltage	$V_{CC} = 5V$ and $T_A = 25^\circ C$		1.7	2.4 V
V_{IT-}	Negative-going input threshold voltage	$V_{CC} = 5V$ and $T_A = 25^\circ C$		0.8	1.2 V
V_{hys}	Input hysteresis ($V_{IT+} - V_{IT-}$)			0.2	0.5 V
r_i	Input resistance	$V_I = \pm 3V$ to $\pm 25V$		3	5 7 kΩ

- (1) Test conditions are C1 to C4 = 0.1μF at $V_{CC} = 5V + 0.5V$.
(2) All typical values are at $V_{CC} = 5V$ and $T_A = 25^\circ C$.

5.8 Switching Characteristics: Driver

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted; see 图 7-1)⁽¹⁾

PARAMETER	TEST CONDITIONS	MIN	TYP ⁽²⁾	MAX	UNIT
Maximum data rate	$C_L = 50$ to 1000pF , one D_{OUT} switching, and $R_L = 3\text{k}\Omega$ to $7\text{k}\Omega$ (see 图 6-1)	120			kbit/s
$t_{PLH(D)}$ Propagation delay time, low- to high-level output	$C_L = 2500\text{pF}$, all drivers loaded, and $R_L = 3\text{k}\Omega$ (see 图 6-1)		2		μs
$t_{PHL(D)}$ Propagation delay time, high- to low-level output	$C_L = 2500\text{pF}$, all drivers loaded, and $R_L = 3\text{k}\Omega$ (see 图 6-1)		2		μs
$t_{sk(p)}$ Pulse skew ⁽³⁾	$C_L = 150$ to 2500pF and $R_L = 3\text{k}\Omega$ to $7\text{k}\Omega$ (see 图 6-2)		300		ns
$SR(tr)$ Slew rate, transition region	$C_L = 50$ to 1000pF , $V_{CC} = 5\text{V}$, and $R_L = 3\text{k}\Omega$ to $7\text{k}\Omega$ (see 图 6-1)	3	6	30	V/ μs

(1) Test conditions are C_1 to $C_4 = 0.1\mu\text{F}$ at $V_{CC} = 5\text{V} + 0.5\text{V}$.

(2) All typical values are at $V_{CC} = 5\text{V}$ and $T_A = 25^\circ\text{C}$.

(3) Pulse skew is defined as $|t_{PLH} - t_{PHL}|$ of each channel of the same device.

5.9 Switching Characteristics: Receiver

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted; see 图 6-3)⁽¹⁾

PARAMETER	TEST CONDITIONS	MIN	TYP ⁽²⁾	MAX	UNIT
$t_{PLH(R)}$ Propagation delay time, low- to high-level output	$C_L = 150\text{pF}$		0.5	10	μs
$t_{PHL(R)}$ Propagation delay time, high- to low-level output	$C_L = 150\text{pF}$		0.5	10	μs
$t_{sk(p)}$ Pulse skew ⁽³⁾			300		ns

(1) Test conditions are C_1 to $C_4 = 0.1\mu\text{F}$ at $V_{CC} = 5\text{V} + 0.5\text{V}$.

(2) All typical values are at $V_{CC} = 5\text{V}$ and $T_A = 25^\circ\text{C}$.

(3) Pulse skew is defined as $|t_{PLH} - t_{PHL}|$ of each channel of the same device.

5.10 Typical Characteristics

$T_A = 25^\circ\text{C}$ (unless otherwise noted)

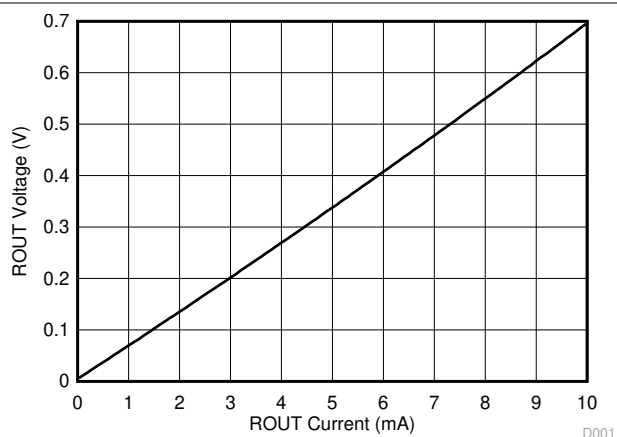


图 5-1. Receiver V_{OL} vs Output Current

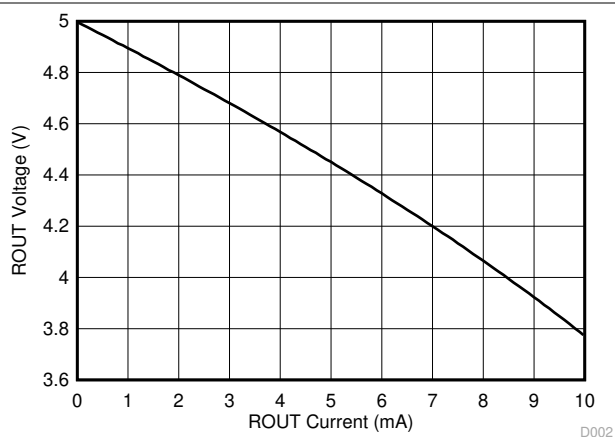


图 5-2. Receiver V_{OH} vs Output Current

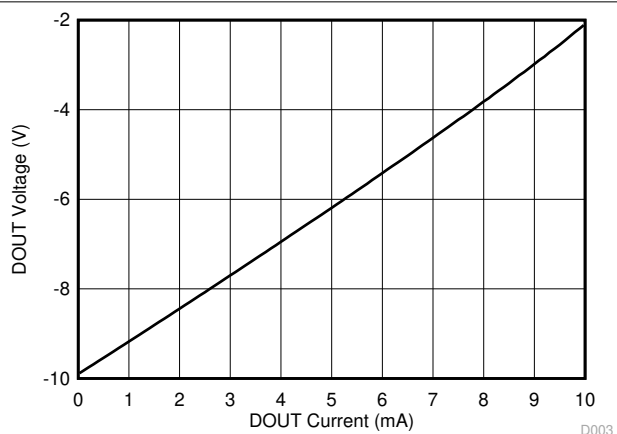


图 5-3. Driver V_{OL} vs Output Current

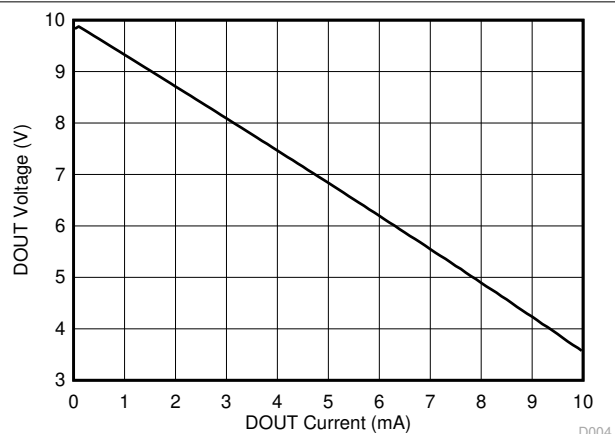


图 5-4. Driver V_{OH} vs Output Current

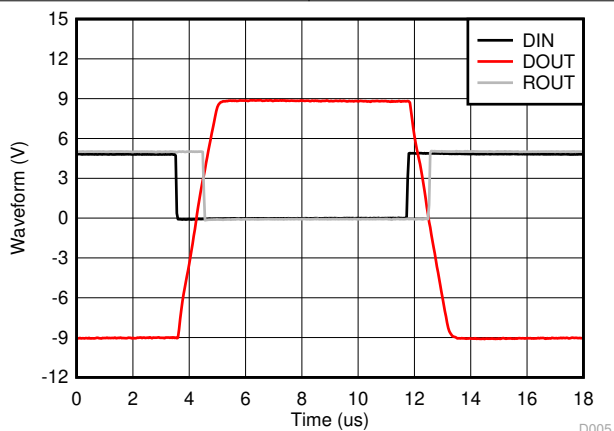
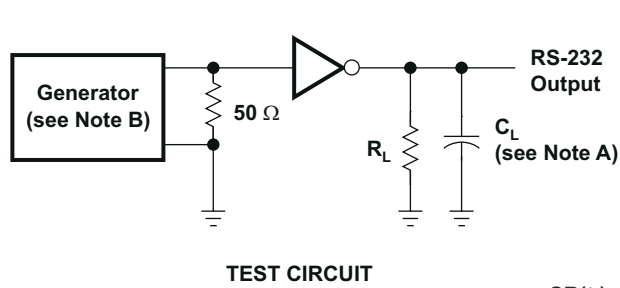
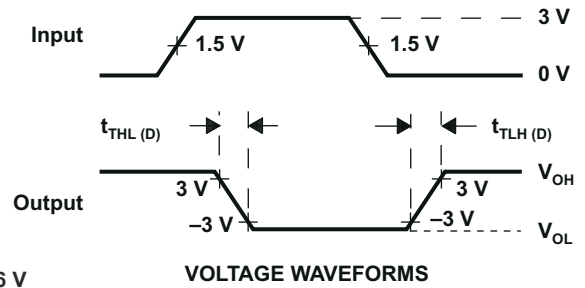


图 5-5. Driver and Receiver Loopback Waveforms

Parameter Measurement Information



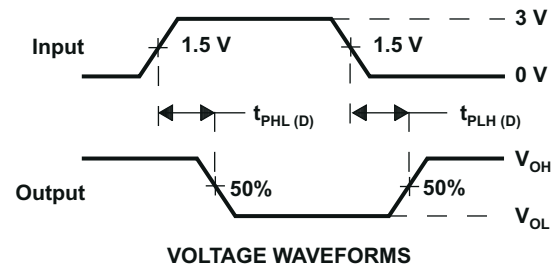
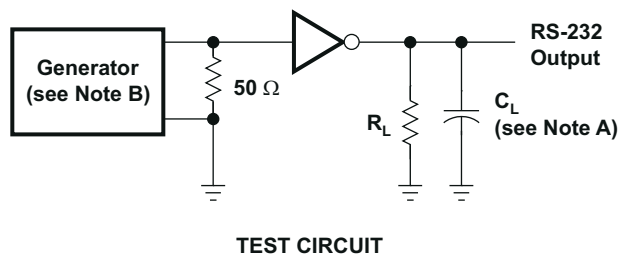
$$SR(t_f) = \frac{6 \text{ V}}{t_{THL(D)} \text{ or } t_{TLH(D)}}$$



NOTES: A. C_L includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR = 120 kbit/s, $Z_O = 50 \Omega$, 50% duty cycle, $t_r \leq 10 \text{ ns}$, $t_f \leq 10 \text{ ns}$.

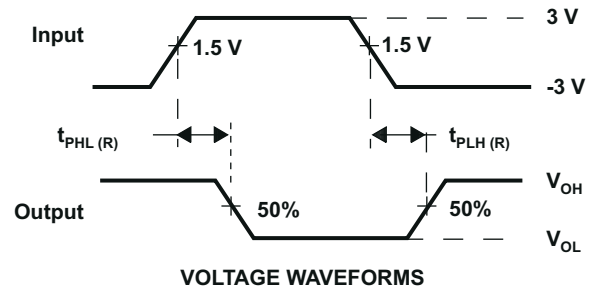
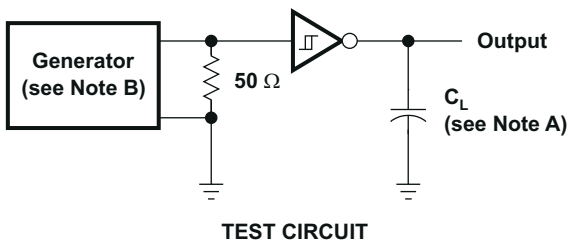
图 6-1. Driver Slew Rate



NOTES: A. C_L includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR = 120 kbit/s, $Z_O = 50 \Omega$, 50% duty cycle, $t_r \leq 10 \text{ ns}$, $t_f \leq 10 \text{ ns}$.

图 6-2. Driver Pulse Skew



NOTES: A. C_L includes probe and jig capacitance.

B. The pulse generator has the following characteristics: $Z_O = 50 \Omega$, 50% duty cycle, $t_r \leq 10 \text{ ns}$, $t_f \leq 10 \text{ ns}$.

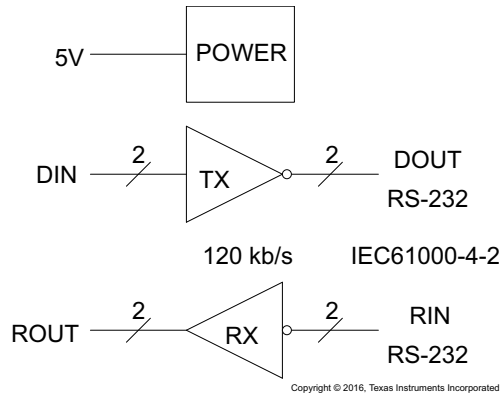
图 6-3. Receiver Propagation Delay Times

6 Detailed Description

6.1 Overview

The TRS202E device is a dual driver and receiver that includes a capacitive voltage generator using four capacitors to supply TIA/EIA-232-F voltage levels from a single 5V supply. All RS-232 pins have 15kV HBM and IEC61000-4-2 Air-Gap discharge protection. RS-232 pins also have 8-kV IEC61000-4-2 contact discharge protection. Each receiver converts TIA/EIA-232-F inputs to 5V TTL/CMOS levels. These receivers have shorted and open fail safe. The receiver can accept up to $\pm 30\text{V}$ inputs and decode inputs as low as $\pm 3\text{V}$. Each driver converts TTL/CMOS input levels into TIA/EIA-232-F levels. Outputs are protected against shorts to ground.

6.2 Functional Block Diagram



6.3 Feature Description

6.3.1 Power

The power block increases and inverts the 5V supply for the RS-232 driver using a charge pump that requires four 0.1 μF or 1 μF external capacitors.

6.3.2 RS-232 Driver

Two drivers interface standard logic levels to RS-232 levels. The driver inputs do not have internal pullup resistors. Do not float the driver inputs.

6.3.3 RS-232 Receiver

Two Schmitt trigger receivers interface RS-232 levels to standard logic levels. Each receiver has an internal 5-k Ω load to ground. An open input results in a high output on R_{OUT}.

6.4 Device Functional Modes

6.4.1 V_{CC} Powered by 5V

The device is in normal operation when powered by 5V.

6.4.2 V_{CC} Unpowered

When TRS202E is unpowered, it can be safely connected to an active remote RS-232 device.

6.4.3 Truth Tables

表 6-1 和 表 6-2 list the function for each driver and receiver (respectively).

表 6-1. Function Table for Each Driver

INPUT DIN ⁽¹⁾	OUTPUT DOUT
L	H
H	L

(1) H = high level, L = low level

表 6-2. Function Table for Each Receiver

INPUT RIN ⁽¹⁾	OUTPUT ROUT
L	H
H	L
Open	H

(1) H = high level, L = low level,
Open = input disconnected or connected driver off

7 Application and Implementation

备注

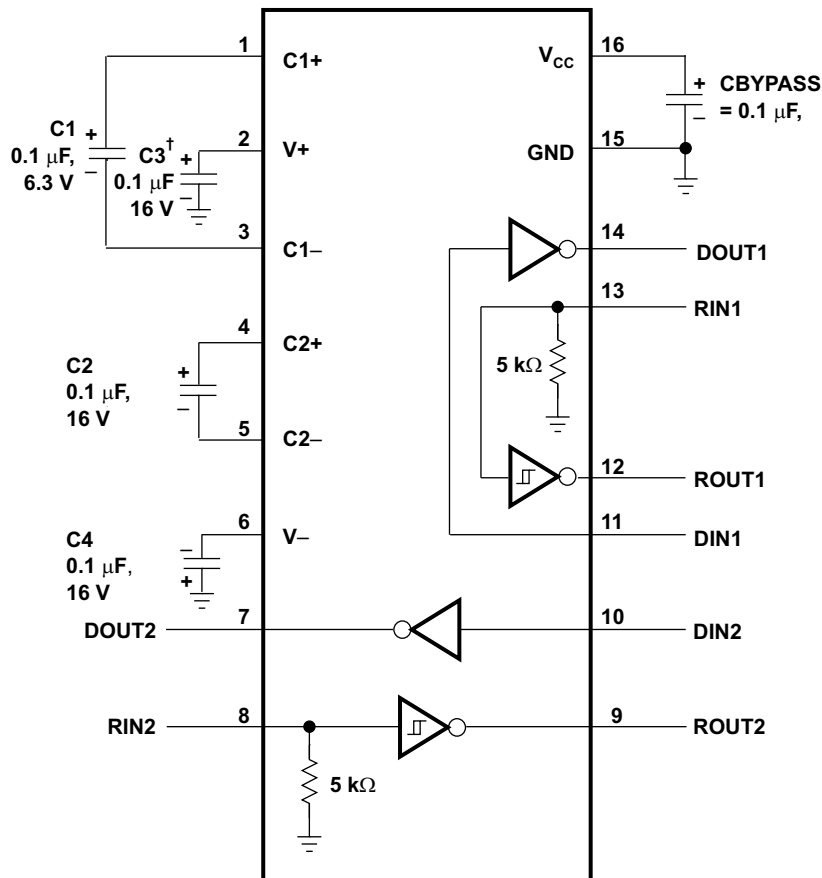
以下应用部分中的信息不属于 TI 器件规格的范围，TI 不担保其准确性和完整性。TI 的客户应负责确定器件是否适用于其应用。客户应验证并测试其设计，以确保系统功能。

7.1 Application Information

For proper operation, add capacitors as shown in 图 7-1. Pins 9 through 12 connect to UART or general purpose logic lines. RS-232 lines on pins 7, 8, 13, and 14 connect to a connector or cable.

7.2 Typical Application

Two driver and two receiver channels are supported for full duplex transmission with hardware flow control. The two $5\text{k}\Omega$ -resistors are internal to the TRS202E.



† C3 can be connected to V_{CC} or GND.

NOTES: A. Resistor values shown are nominal.

B. Nonpolarized ceramic capacitors are acceptable. If polarized tantalum or electrolytic capacitors are used, they should be connected as shown.

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图 7-1. Typical Operating Circuit and Capacitor Values

7.2.1 Design Requirements

- V_{CC} minimum is 4.5V and maximum is 5.5V.
- Maximum recommended bit rate is 120kbps.

7.2.2 Detailed Design Procedure

7.2.2.1 Capacitor Selection

The capacitor type used for C1 through C4 is not critical for proper operation. The TRS202E requires 0.1 μ F capacitors. 1- μ F capacitors are also acceptable. TI recommends ceramic dielectrics. When using the minimum recommended capacitor values, ensure the capacitance value does not degrade excessively as the operating temperature varies. If in doubt, use capacitors with a larger (for example, 2 $\times$) nominal value. The capacitors' effective series resistance (ESR), which usually rises at low temperatures, influences the amount of ripple on $V+$ and $V-$.

Bypass V_{CC} to ground with at least 0.1 μ F. In applications sensitive to power-supply noise generated by the charge pumps, decouple V_{CC} to ground with a capacitor the same size as (or larger than) the charge-pump capacitors (C1 to C4).

7.2.3 Application Curves

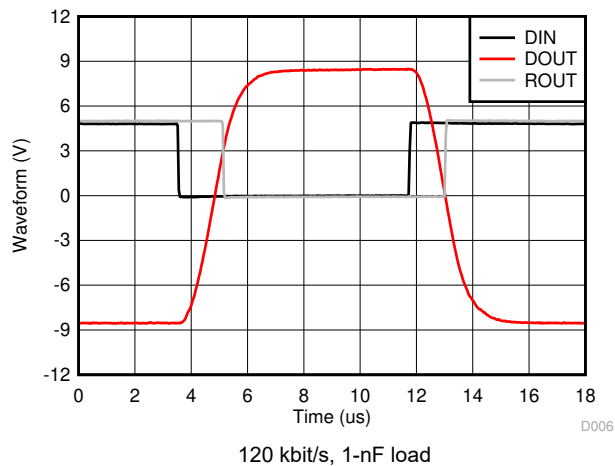


图 7-2. Driver and Receiver Loopback Signal

7.3 Power Supply Recommendations

The V_{CC} voltage must be connected to the same power source used for logic device connected to DIN and ROUT pins. V_{CC} must be between 4.5V and 5.5V.

7.4 Layout

7.4.1 Layout Guidelines

Keep the external capacitor traces short. This is more important on C1 and C2 nodes that have the fastest rise and fall times. Make the impedance from TRS202E ground pin and circuit boards ground plane as low as possible for best ESD performance. Use wide metal and multiple vias on both sides of ground pin.

7.4.2 Layout Example

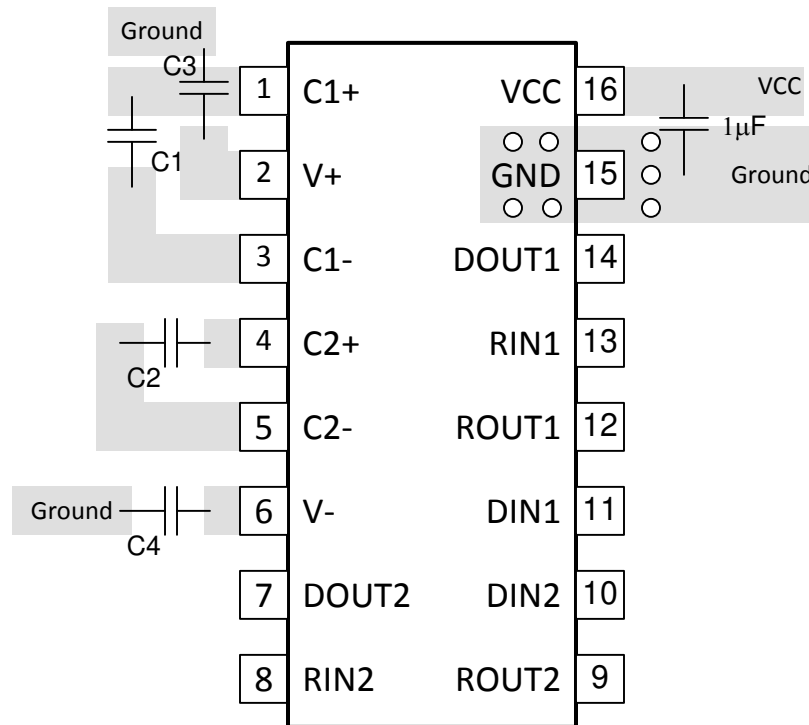


图 7-3. TRS202E Layout

8 Device and Documentation Support

8.1 接收文档更新通知

要接收文档更新通知，请导航至 ti.com 上的器件产品文件夹。点击 [订阅更新](#) 进行注册，即可每周接收产品信息更改摘要。有关更改的详细信息，请查看任何已修订文档中包含的修订历史记录。

8.2 支持资源

TI E2E™ 支持论坛 是工程师的重要参考资料，可直接从专家获得快速、经过验证的解答和设计帮助。搜索现有解答或提出自己的问题可获得所需的快速设计帮助。

链接的内容由各个贡献者“按原样”提供。这些内容并不构成 TI 技术规范，并且不一定反映 TI 的观点；请参阅 TI 的《[使用条款](#)》。

8.3 Trademarks

TI E2E™ is a trademark of Texas Instruments.

所有商标均为其各自所有者的财产。

8.4 静电放电警告



静电放电 (ESD) 会损坏这个集成电路。德州仪器 (TI) 建议通过适当的预防措施处理所有集成电路。如果不遵守正确的处理和安装程序，可能会损坏集成电路。

ESD 的损坏小至导致微小的性能降级，大至整个器件故障。精密的集成电路可能更容易受到损坏，这是因为非常细微的参数更改都可能会导致器件与其发布的规格不相符。

8.5 术语表

TI 术语表

本术语表列出并解释了术语、首字母缩略词和定义。

9 Revision History

注：以前版本的页码可能与当前版本的页码不同

Changes from Revision E (November 2016) to Revision F (February 2024)	Page
• 更改了 <i>封装信息</i> 表.....	1
• Changed the <i>Thermal Information</i> table.....	5

Changes from Revision D (November 2012) to Revision E (November 2016)	Page
• 添加了 <i>ESD</i> 等级表、特性说明部分、器件功能模式、应用和实现部分、电源相关建议部分、布局部分、器件和文档支持部分以及机械、封装和可订购信息部分.....	1
• 删除了 <i>订购信息</i> 表，请参阅数据表末尾的 <i>封装选项附录</i>	1
• Changed Package thermal impedance, $R_{\theta JA}$, values in Thermal Information table From: 73°C/W To: 76.7°C/W (D), From: 57°C/W To: 77.1°C/W (DW), From: 67°C/W To: 44.1°C/W (N), and From: 108°C/W To: 101.7°C/W (PW).....	5

Changes from Revision C (May 2010) to Revision D (November 2012)	Page
• Fixed I_{OS} values in <i>Electrical Characteristics</i> table, changed - to $\pm$	5

10 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TRS202ECDWR	ACTIVE	SOIC	DW	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	TRS202EC	Samples
TRS202ECN	ACTIVE	PDIP	N	16	25	RoHS & Non-Green	NIPDAU	N / A for Pkg Type	0 to 70	TRS202ECN	Samples
TRS202EIDR	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TRS202EI	Samples
TRS202EIDW	ACTIVE	SOIC	DW	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TRS202EI	Samples
TRS202EIDWR	ACTIVE	SOIC	DW	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TRS202EI	Samples
TRS202EIN	ACTIVE	PDIP	N	16	25	RoHS & Non-Green	NIPDAU	N / A for Pkg Type	-40 to 85	TRS202EIN	Samples
TRS202EIPWR	ACTIVE	TSSOP	PW	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	RU02EI	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TRS202ECDWR	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1
TRS202EIDR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
TRS202EIDWR	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1
TRS202EIPWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TRS202ECDWR	SOIC	DW	16	2000	350.0	350.0	43.0
TRS202EIDR	SOIC	D	16	2500	356.0	356.0	35.0
TRS202EIDWR	SOIC	DW	16	2000	350.0	350.0	43.0
TRS202EIPWR	TSSOP	PW	16	2000	367.0	367.0	35.0

TUBE

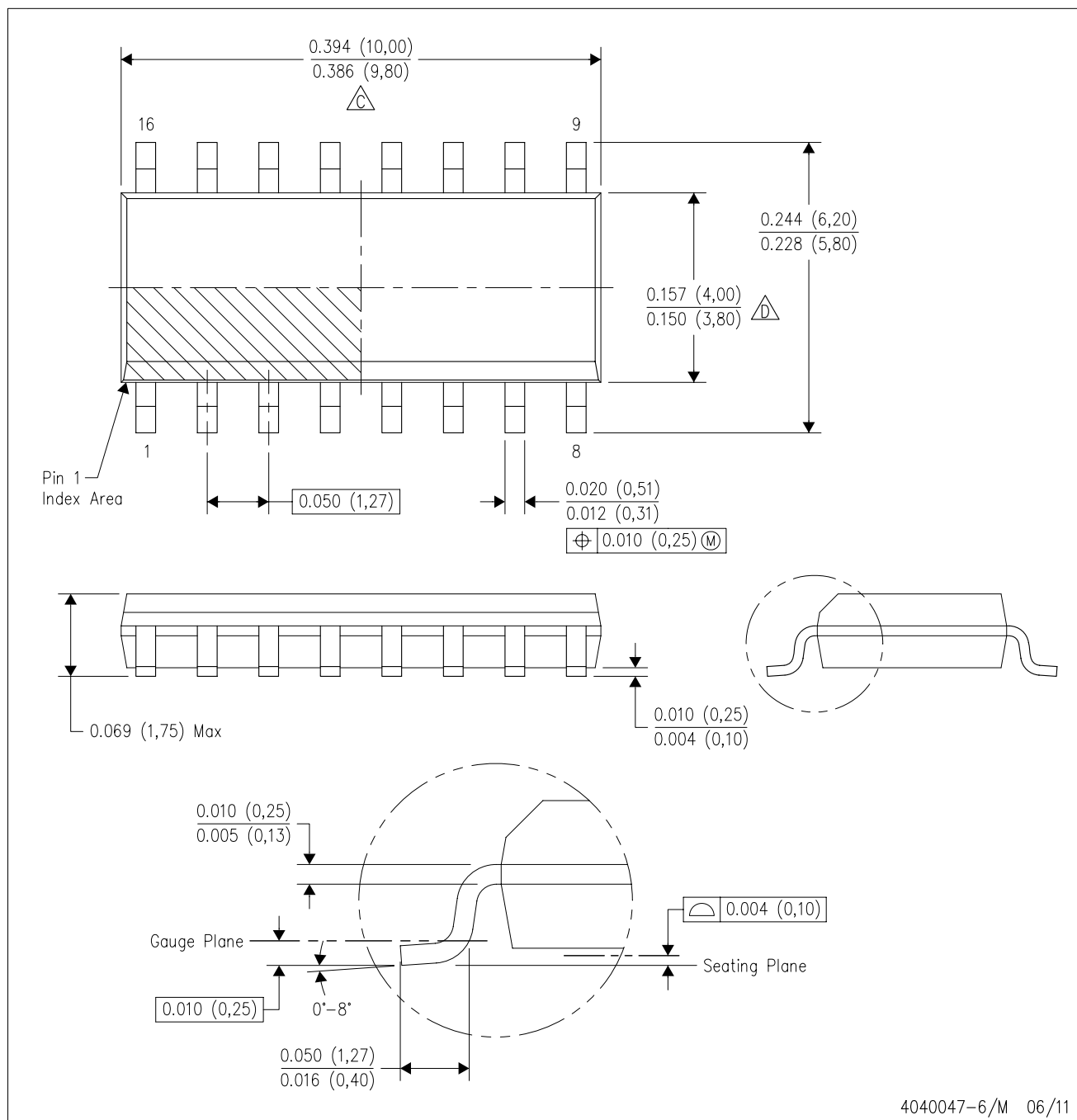


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
TRS202ECN	N	PDIP	16	25	506	13.97	11230	4.32
TRS202EIDW	DW	SOIC	16	40	506.98	12.7	4826	6.6
TRS202EIN	N	PDIP	16	25	506	13.97	11230	4.32

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE

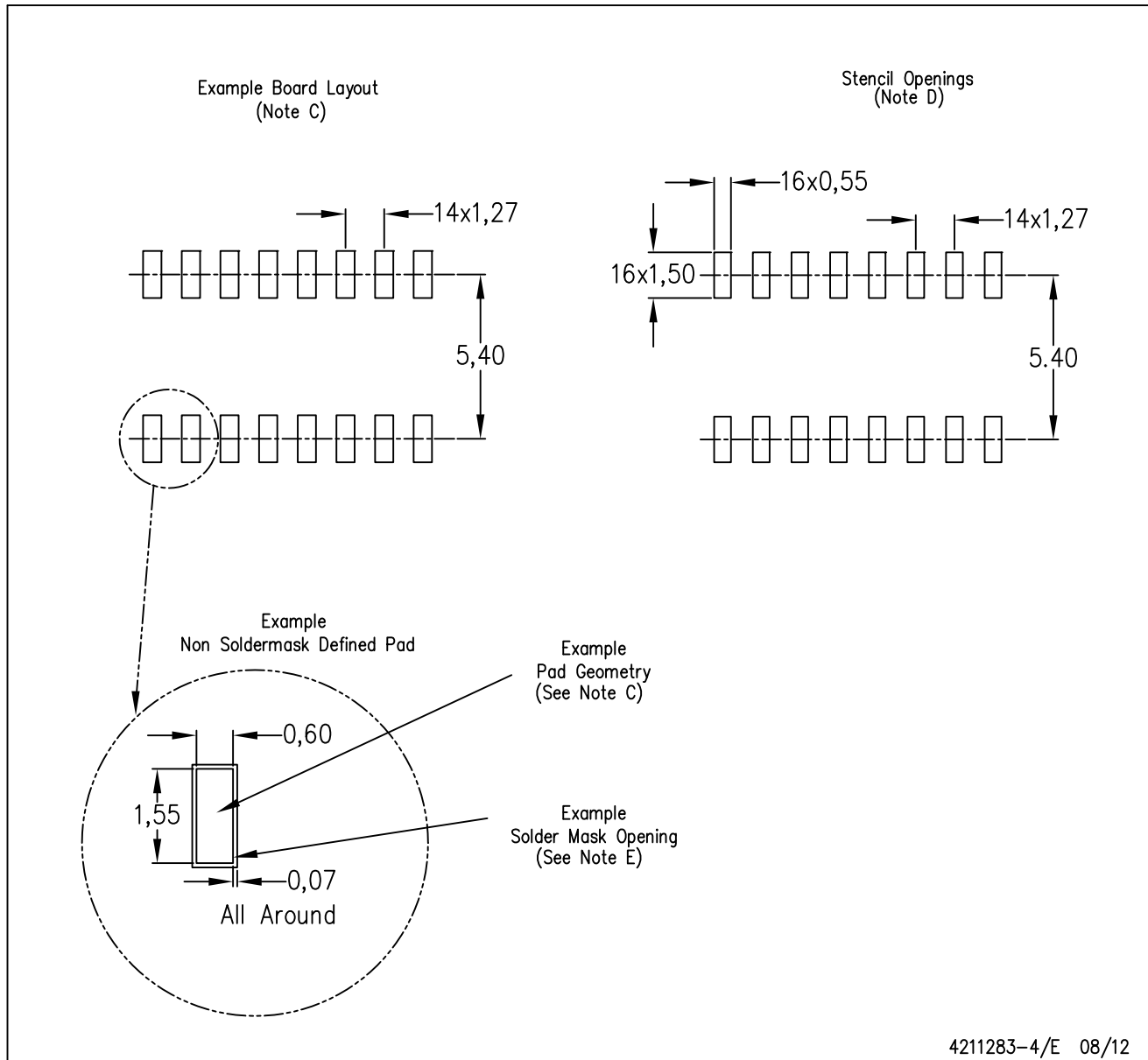


4040047-6/M 06/11

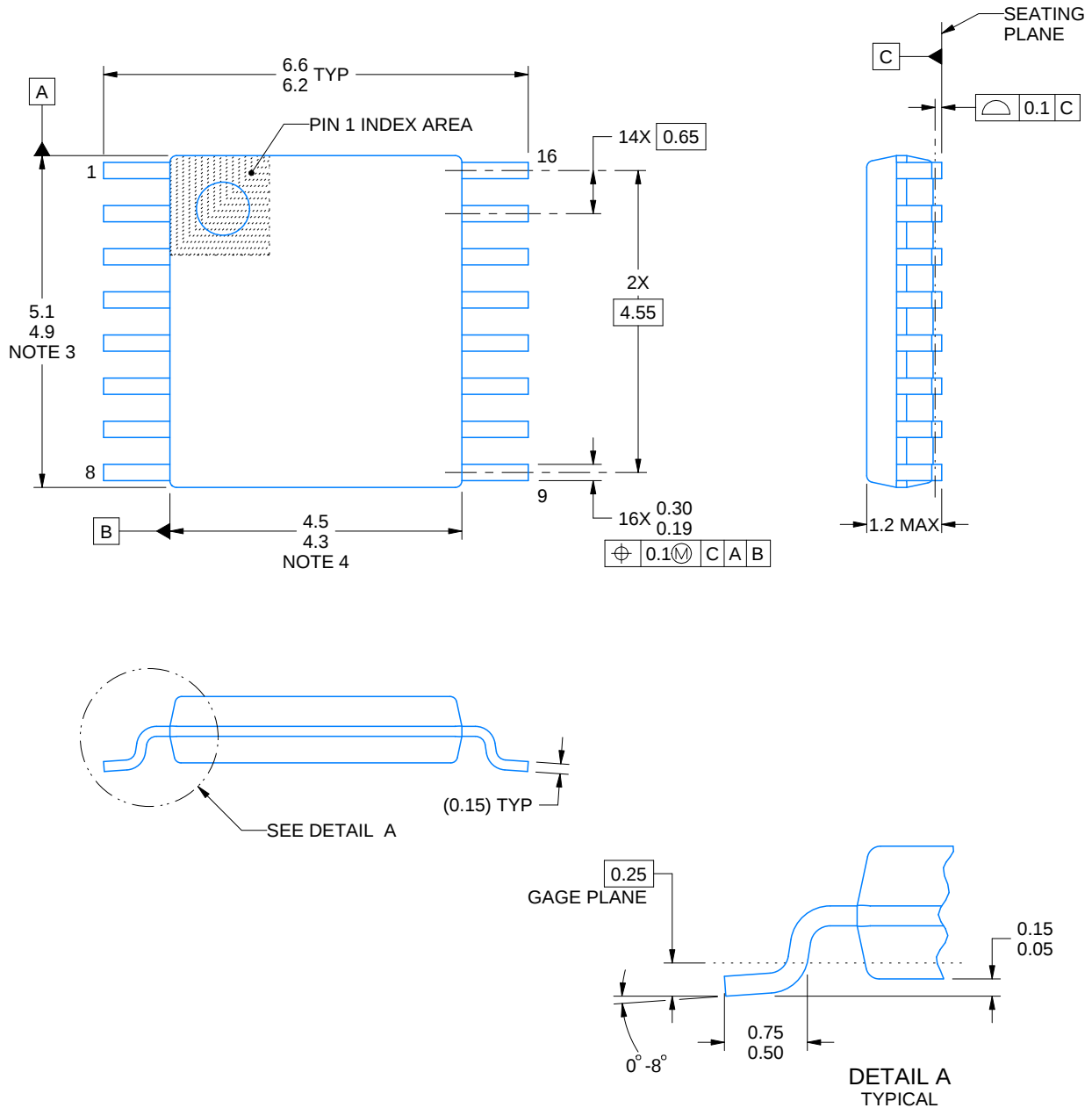
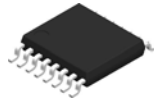
- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AC.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



4220204/A 02/2017

NOTES:

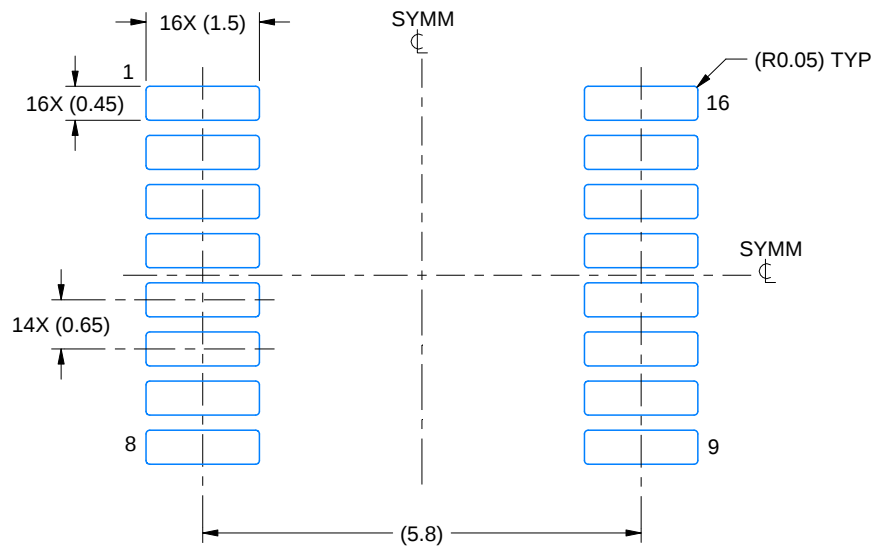
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

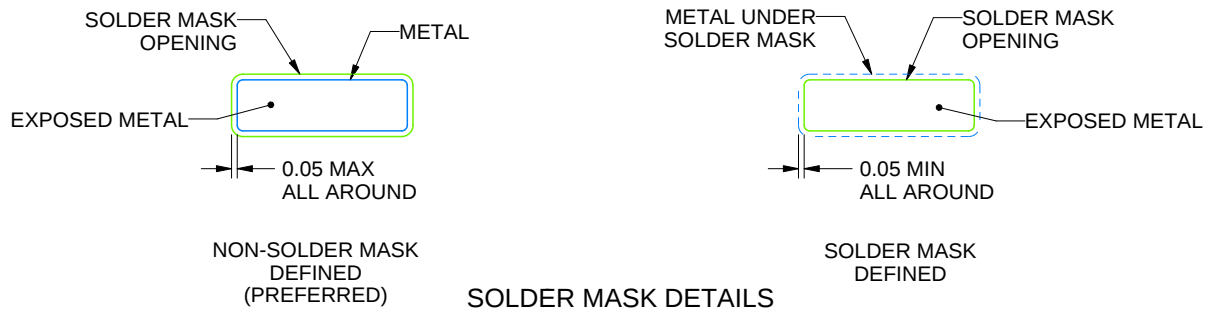
PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



4220204/A 02/2017

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

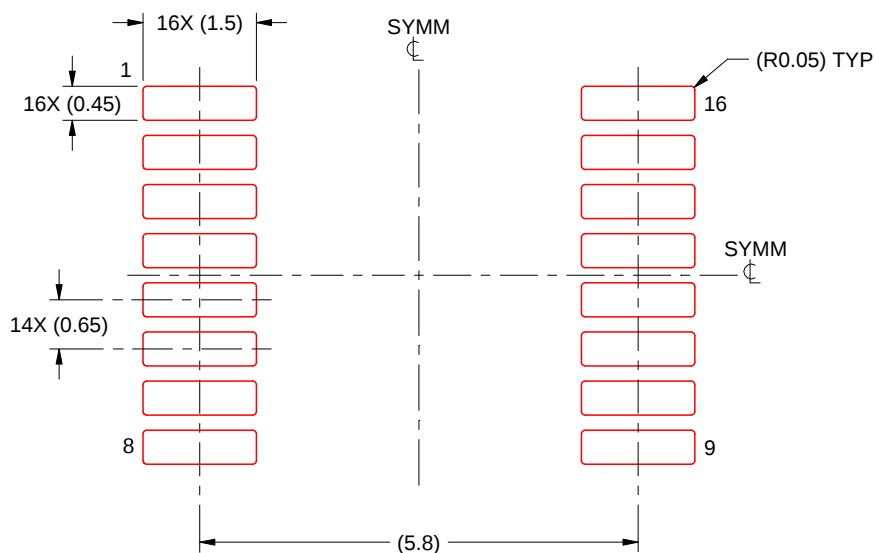
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220204/A 02/2017

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

GENERIC PACKAGE VIEW

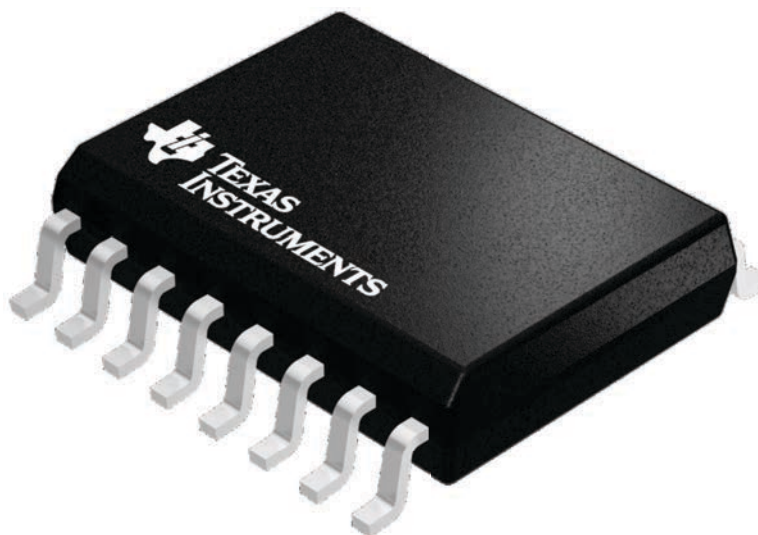
DW 16

SOIC - 2.65 mm max height

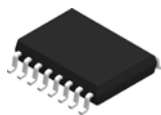
7.5 x 10.3, 1.27 mm pitch

SMALL OUTLINE INTEGRATED CIRCUIT

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.



4224780/A

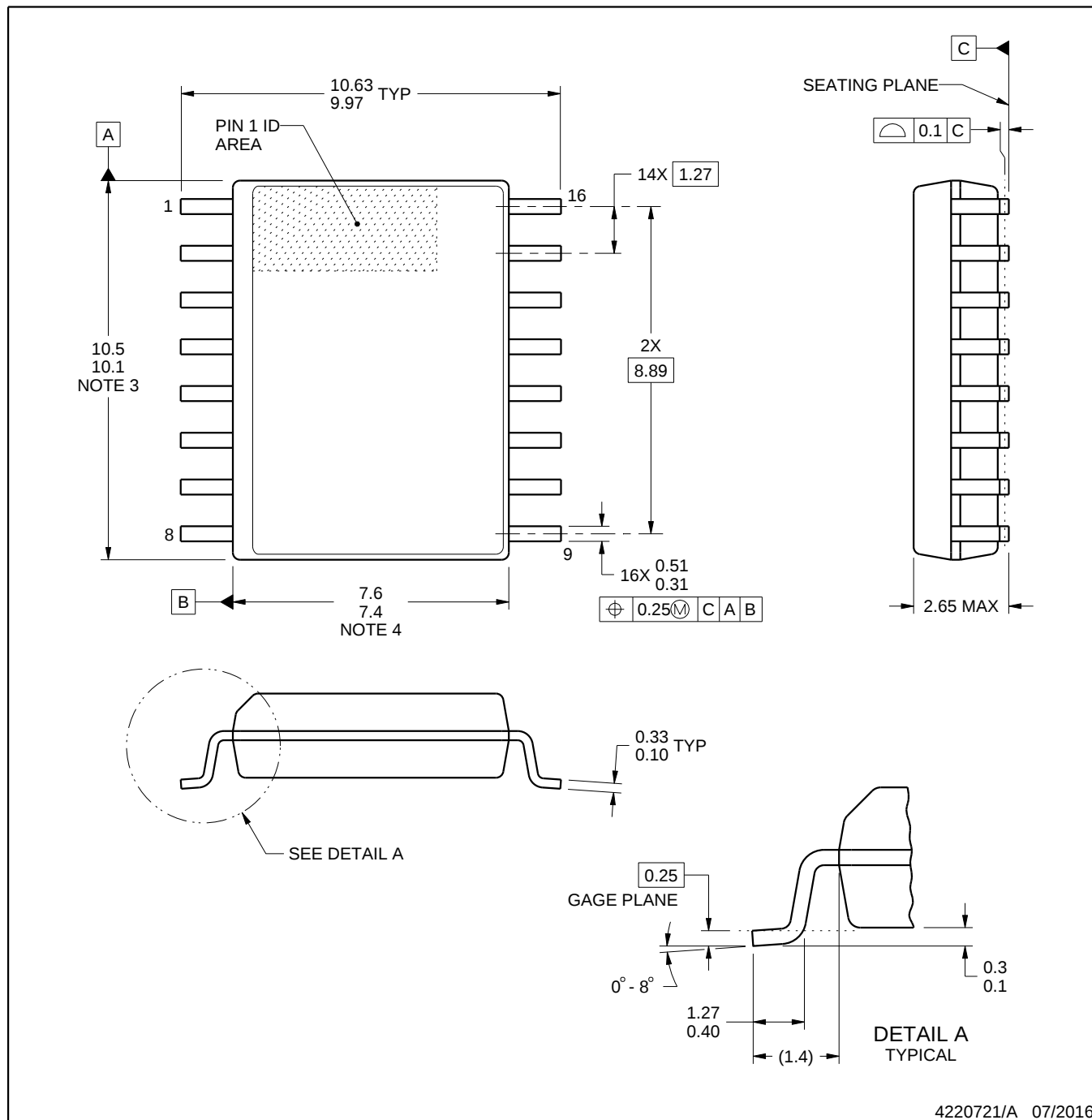


DW0016A

PACKAGE OUTLINE

SOIC - 2.65 mm max height

SOIC



4220721/A 07/2016

NOTES:

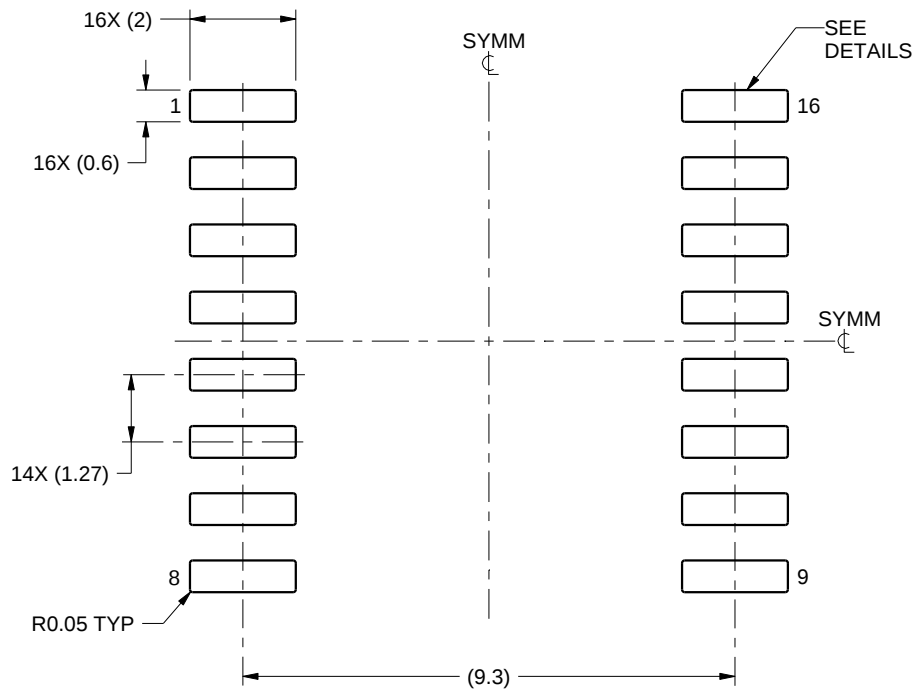
1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.
5. Reference JEDEC registration MS-013.

EXAMPLE BOARD LAYOUT

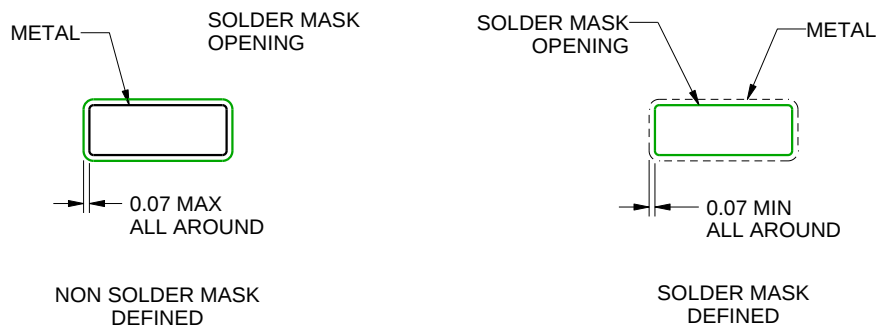
DW0016A

SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE
SCALE:7X



SOLDER MASK DETAILS

4220721/A 07/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

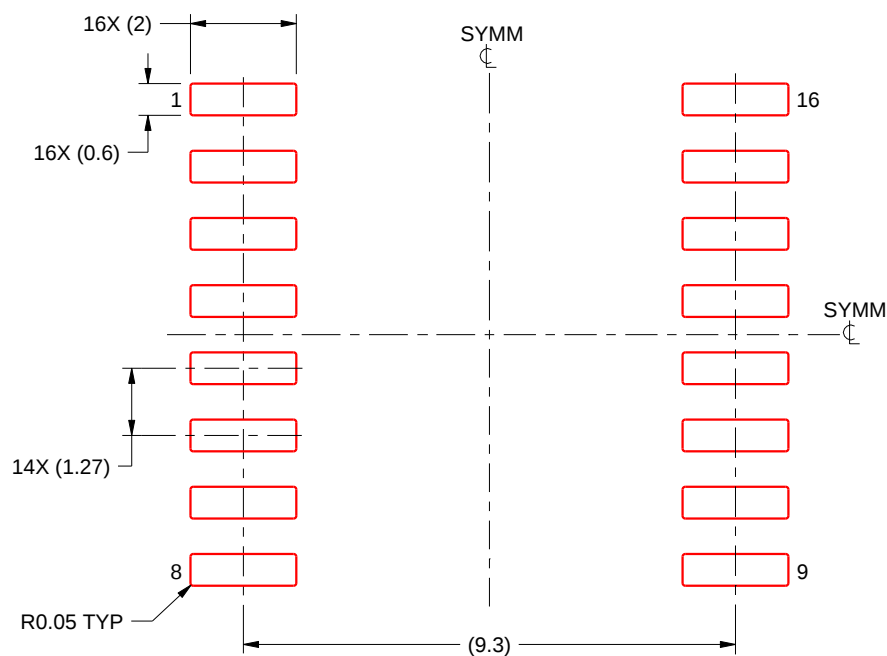
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DW0016A

SOIC - 2.65 mm max height

SOIC



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:7X

4220721/A 07/2016

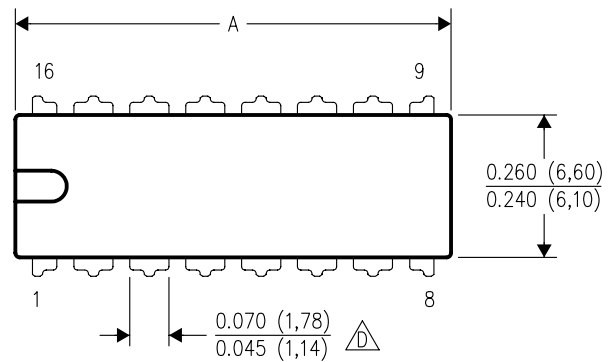
NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

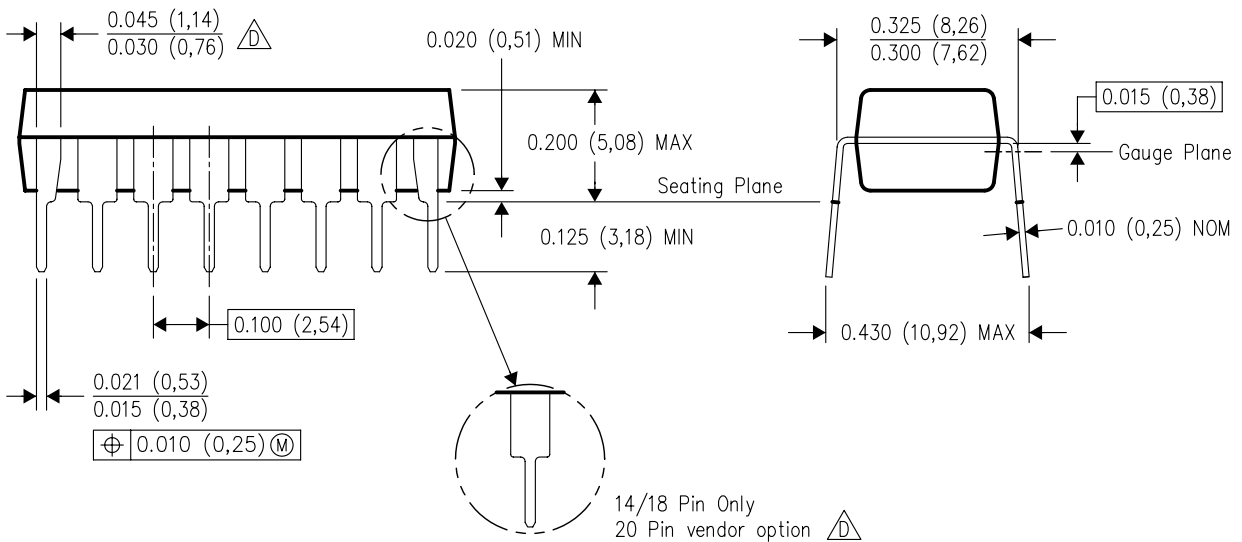
N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



PINS **	14	16	18	20
DIM				
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

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